

CHIPS Act Mini-Symposium Room 122 - Session CPS-MoM

CHIPS Act Mini-Symposium

Moderators: Alain Diebold, University at Albany-SUNY, Erica Douglas, Sandia National Laboratories, Timothy Gessert, Gessert Consulting

8:45am **CPS-MoM-3 Strategic Roadmapping for Information and Communication Technologies**, Victor Zhirnov, Semiconductor Research Corporation; V. Zhirnov, SRC **INVITED**

Information and Communication Technologies (ICT) is the social-economic growth engine of the modern world. This electronic processing and transmission of information includes the explosion of sensing for real-world applications in many market segments, such as automotive, industrial manufacturing and automation, robotics, health, environmental, etc. The use of ICT continues to grow without bounds driven by the exponential creation of data that must be moved, stored, computed, and communicated. Ever-rising energy demands for information and communication technologies versus global energy production are creating new risks. Therefore, new paradigms need to be discovered in order to dramatically improve energy efficiency of ICT.

In the past, the role of strategic planning for semiconductor industry was met by the International Technology Roadmap for Semiconductors (ITRS), serving as a master plan that provided manufacturers, designers, and equipment suppliers with direction years in advance. By providing a common framework for coordination across semiconductor industry stakeholders, technology development efforts were efficient and aligned. However, the dissolution of the ITRS in 2015 left a void, leading to years of disjointed efforts. Recognizing the need for unified guidance, the industry rallied for the creation of new strategic plans, which yielded the 2030 Decadal Plan for Semiconductors (identifies the “What”) and the Microelectronics and Advanced Packaging Technologies (MAPT) Roadmap (identifies the “How”) were developed. These comprehensive plans outline ambitious goals for the industry's future.

Inventing the next hardware/software ICT paradigm is a tall order. However, it is achievable if the right questions are asked and the right resources are put in place. These steps are outlined in the Decadal Plan and in the MAPT Roadmap, which emphasize the need for radical new solutions for future ICT, including sustainability and workforce development.

9:15am **CPS-MoM-5 Challenges and Opportunities in Characterization and Metrology for the Microelectronics and Advanced Packaging Technologies (MAPT) Roadmap**, Markus Kuhn, Rigaku; A. Diebold, SUNY Polytechnic Institute, Albany **INVITED**

The recently released Microelectronics and Advanced Packaging Technologies (MAPT) Roadmap represents the collective efforts of hundreds of individuals representing >100 organizations from government, academia, and industry. The MAPT Roadmap directly supports the Chips and Science Act, led by the U.S. Department of Commerce, in efforts to develop a robust domestic semiconductor ecosystem.

The metrology chapter describes the characterization and metrology requirements for all areas of the MAPT Roadmap including Materials and Devices through Advanced Packaging and Heterogeneous Integration and Systems. Metrology measurements enable all aspects of semiconductor materials and device research, development, and manufacturing, therefore making support for this area critical to meeting technology objectives.

This talk will highlight the importance of continued metrology development and assess the key challenges facing this segment for the next 10+ years. Some of the key challenges and initiatives are highlighted below.

1. Manufacturing-ready 3D metrology.
2. Lab to fab transition to introduce new capabilities into manufacturing.
3. Accelerating lab metrology output (wafer coverage, precision, throughput).
4. Enabling and incorporating DFM (design for metrology,) ML/AI, hybrid metrology concepts as part of a holistic process, test, and simulation ecosystem.

9:45am **CPS-MoM-7 CHIPS Act and Optoelectronics, Devices, and AI/ML**, Volker Sorger, University of Florida **INVITED**

What is the CHIPS Act? The bipartisan CHIPS and Science Act signed into action in 2022 was a seminal action; for the first time since World War II (i.e. the Manhattan project) an economic stimulus package for a single industry was signed. The federal focus to re-shore manufacturing capabilities (\$39B) along with R&D and workforce stimulus packages (\$11B) is joined by matching funds from the States and the private sector (i.e. corporations, SMEs, venture capital), thus adding multiplication factors to the semiconductor ecosystem.

Why now? Chips having been invented in the U.S. some sixty years ago, have been off-shored since the 2000's to far Asia, mainly due to economic factors. The resulting technological- and supply chain independence became all-too evident during the COVID years. With semiconductors (i.e. chips) being a critical part of modern businesses in virtually all economic sectors, securing and re-vitalizing manufacturing capabilities along with critical R&D projects are timely and, thankfully underway.

What is the Role of Photonics in Chips? Optics provides synergistic and performance extending capabilities in two major ways: a) data interconnects and b) special purpose computing. Optical Interconnects and Advanced Packaging: Starting with the former, the bosonic nature and 1,000x wavefunction difference between photons and matter offers optics to provide low-loss long-distance data links. Unlike fibers, new to the CHIPS activities are that photonics is now considered inside board and even inside the package; the latter stems from the desire to blur-the-lines between what is in the package vs. what is on the board in advanced packaging. In addition to 2.5D interposer (e.g. active optical interposer) packaging strategies, 3D heterogeneous integration (3DHI) solutions are anticipated to provide not just 100x interconnect performance gains (e.g. in units of [Gbps/mm/pj/bit]), but also enable best-of-both world co-design and optimization ‘options’ (i.e. ‘known-best-die’). In regard to Special Purpose Computing, photonic chips offers some interesting benefits but also challenges: the benefits resolve around the ability to i) executing mathematical functions in the optical domain at zero energy, ii) processing data at full bit resolution in their natural domain (no analog-to-digital conversion past the sensor), iii) allowing for high degrees of signal fan-out (e.g. for neuromorphic computing), and iv) enabling real-time computing in the 10's of picosecond range per device (minus RC delays from the optoelectronic components).

10:30am **CPS-MoM-10 Bridging Opportunities and Challenges: Examining a Community College's Role in Preparing Technicians for the Semiconductor Industry**, Nancy Louwagie, Normandale Community College **INVITED**

Community colleges offer the potential to take on a crucial role in preparing the technician workforce for the semiconductor industry. This presentation aims to showcase a vacuum technology program offered at Normandale Community College (Bloomington, MN) as a case study, illustrating how such institutions can serve as hubs for workforce development. Furthermore, it delves into the obstacles faced by community colleges in establishing and sustaining high-tech programs of study.

Opportunities:

1. **Affordability:** Community colleges are recognized as the most cost-effective option in higher education, offering accessible pathways to technical education.
2. **Accessibility:** With campuses spread across states, community colleges ensure geographical inclusivity, providing equitable access to post-secondary education.
3. **Localized Programming:** Community colleges have the flexibility to tailor programs to meet the specific workforce demands of their regions.
4. **Industry Collaboration:** Increasingly, local employers are partnering with community colleges to provide internship and apprenticeship opportunities that enhance students' practical skills and employability prospects.

Challenges:

1. **Financial Sustainability:** Community colleges grapple with financial instability, particularly small programs, which are at constant risk of closure, threatening the continuity of any technician training program.
2. **Faculty Recruitment:** Technical programs require specialized faculty, but community colleges often struggle to attract and retain qualified instructors.

Monday Morning, November 4, 2024

3. Equipment Procurement: Maintaining up-to-date equipment for hands-on learning is essential in technical education, yet community colleges face challenges acquiring and maintaining this equipment.
4. Pandemic Impact on Disadvantaged Students: COVID-19 exacerbated existing disparities, disproportionately affecting students from disadvantaged backgrounds. Academic setbacks pose challenges to program retention and completion rates.

Conclusion: Community colleges can fulfill a critical role in meeting the substantial technician development demands of the semiconductor industry. They are known for delivering affordable, accessible, and regionally tailored programs. However, sustaining and enhancing these initiatives requires addressing financial constraints, faculty shortages, equipment needs, and supporting students, particularly those facing pandemic-related setbacks. Collaborative efforts between educational institutions, industry partners, and policymakers are essential in navigating these challenges and maximizing the potential of community colleges in preparing the semiconductor workforce of tomorrow.

11:00am CPS-MoM-12 CHIPS Act and the Future of the Semiconductor Industry Panel Discussion, *Erica Douglas*, Sandia National Lab

Leading experts will participate in CHIPS Act panel session chaired by Erica Douglas. The panel session will explore aspects of the new initiatives in the semiconductor industry funded by the CHIPS Act. Participants will include the invited speakers for the Chips Act Session.

Author Index

Bold page numbers indicate presenter

— D —

Diebold, A.: CPS-MoM-5, **1**
Douglas, E.: CPS-MoM-12, **2**

— K —

Kuhn, M.: CPS-MoM-5, **1**

— L —

Louwagie, N.: CPS-MoM-10, **1**

— S —

Sorger, V.: CPS-MoM-7, **1**

— Z —

Zhirnov, V.: CPS-MoM-3, **1**